

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,700,794 B2  
APPLICATION NO. : 09/915762  
DATED : March 2, 2004  
INVENTOR(S) : Robert S. Vinson et al.

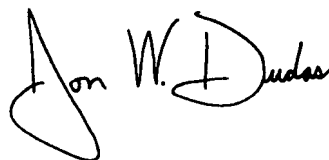
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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 6, Line 63	Delete: "a decoupling" Insert: -- at least one decoupling --
\ Column 6, Line 63	Delete: "on each" Insert: -- on the --
Column 7, Lines 4-5	Delete: "to a die pad and from a die pad to a substrate bonding pad" Insert: -- to the die pads and from the die pads to the substrate bonding pads --
Column 7, Line 19	Delete: "a wire bond" Insert: -- the wire bond --
Column 8, Line 10	Delete: "to a logic pin and from a logic pin" Insert: -- to the logic pin and from the logic pin --
Column 8, Line 11	Delete: "a substrate" Insert: -- the substrate --

Signed and Sealed this

Eighteenth Day of September, 2007



JON W. DUDAS  
*Director of the United States Patent and Trademark Office*